

Low Power Nanoelectronics for Post-CMOS Reconfigurable ICs

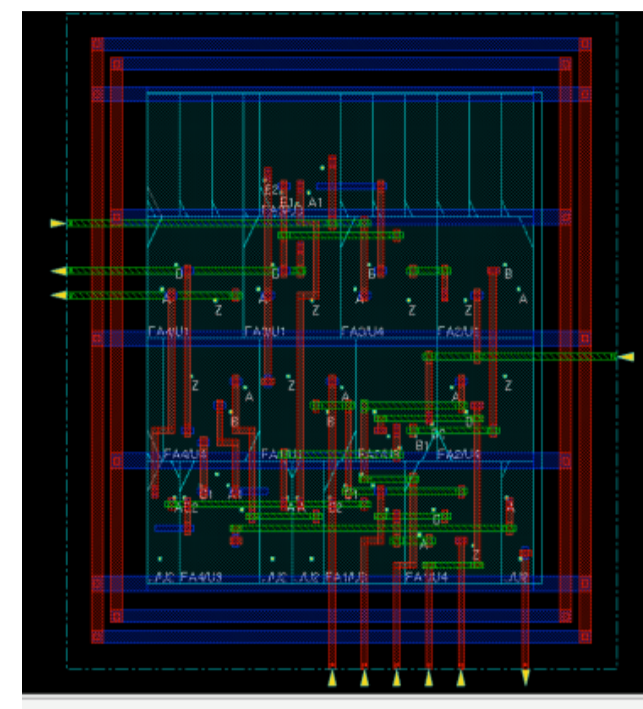
Santosh Khasanvis, Csaba Andras Moritz, University of Massachusetts Amherst



Challenges with Existing Technology

- Technological: Arbitrary layouts & sizing; stringent overlay (3nm), variability (1.3nm CD) at 16nm node – ITRS 2011
- Power/Thermal
- Economic: Escalating manufacturing cost, design cost for custom IC development

CMOS Arbitrary Layouts

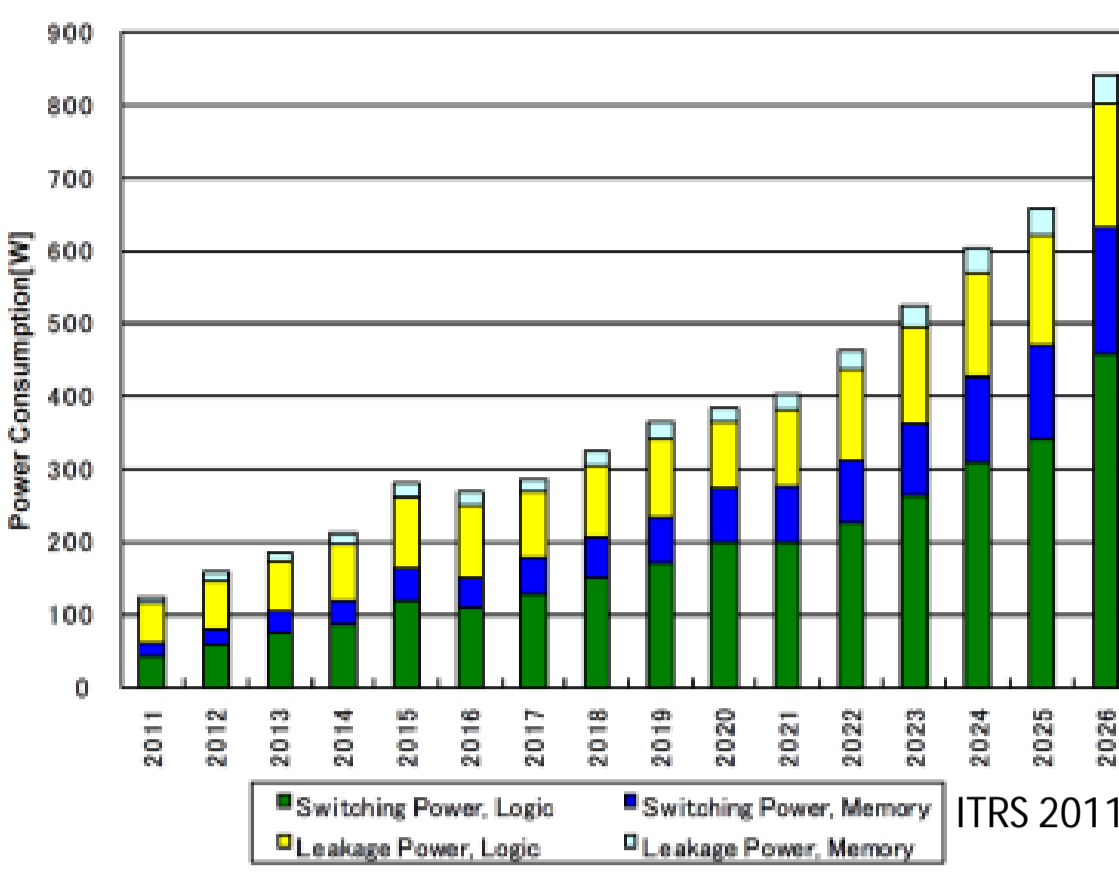


ITRS '11 CMOS Projections

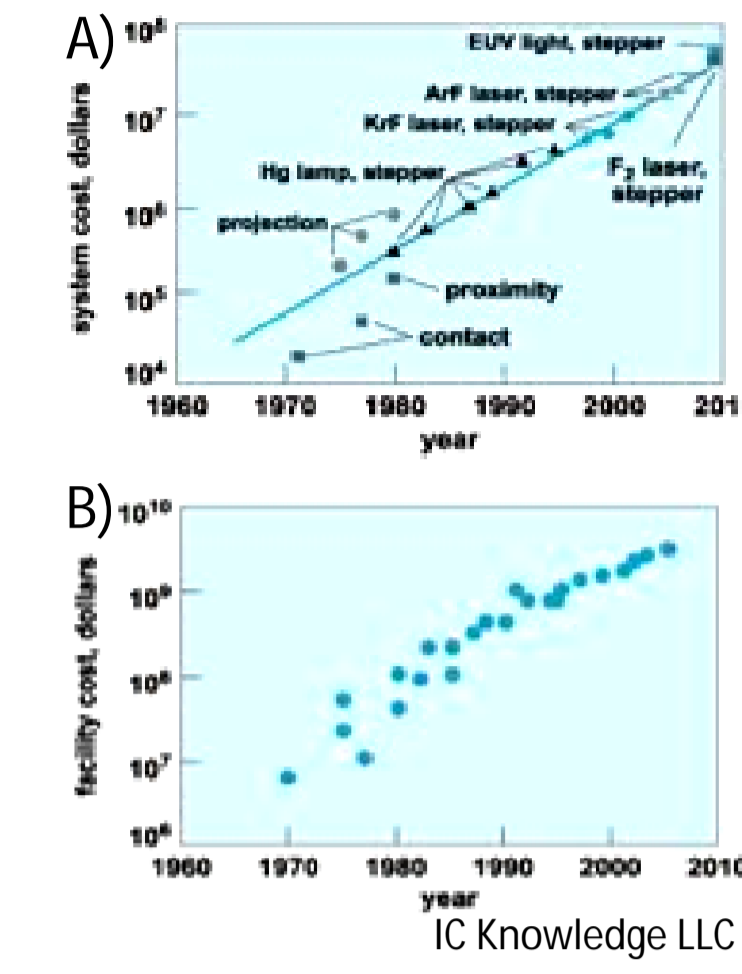
Year	MPU Gate 3σ (nm)	Overlay 3σ (nm)	Gate CD 3σ (nm)
2013	23	5.3	2.1
2014	25	4.9	1.9
2015	22	4.2	1.7
2016	20	3.8	1.6
2017	18	3.4	1.5
2018	16	3	1.3
2019	14	2.7	1.2
2020	12	2.4	1.1
2021	11	2.1	1
2022	10	1.9	0.9
2023	8.8	1.7	0.8
2024	7.9	1.5	0.8

Legend: Manufacturing Solutions Known (Green), Manufacturing Solutions Not Known (Red)

Power Consumption Trends



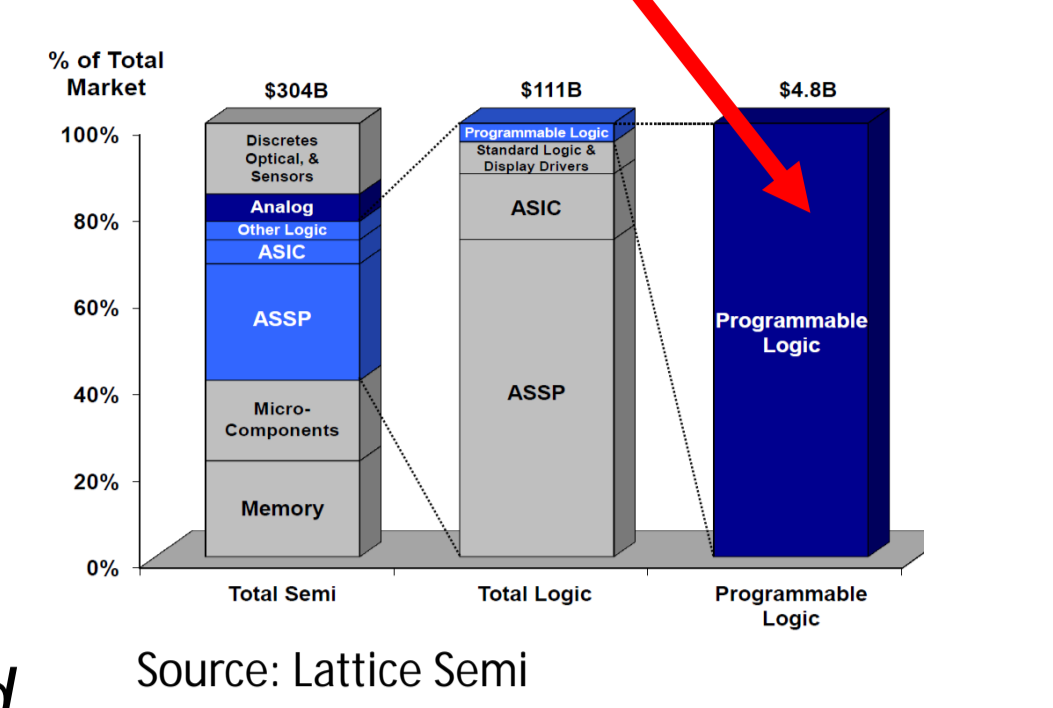
Trends in (A) Lithographic Tool Costs and (B) Facility Costs



Reconfigurable Computing

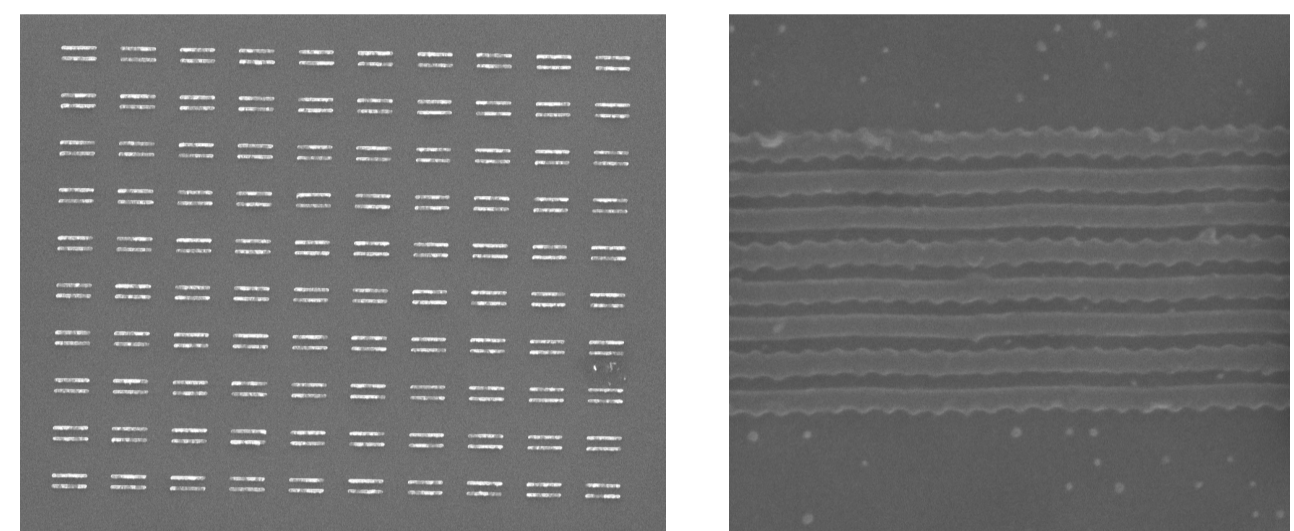
- Post-manufacturing programmability; Reduced time to market; Low design costs
- Inefficient emulated reconfigurability
- Explore new paradigms: Emerging nanomaterials and phenomena

Scope for Reconfigurable Systems

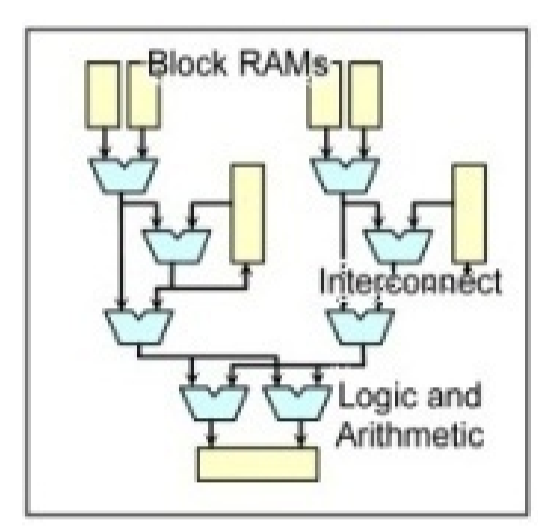


Reconfigurable Nanowire Computing Fabric

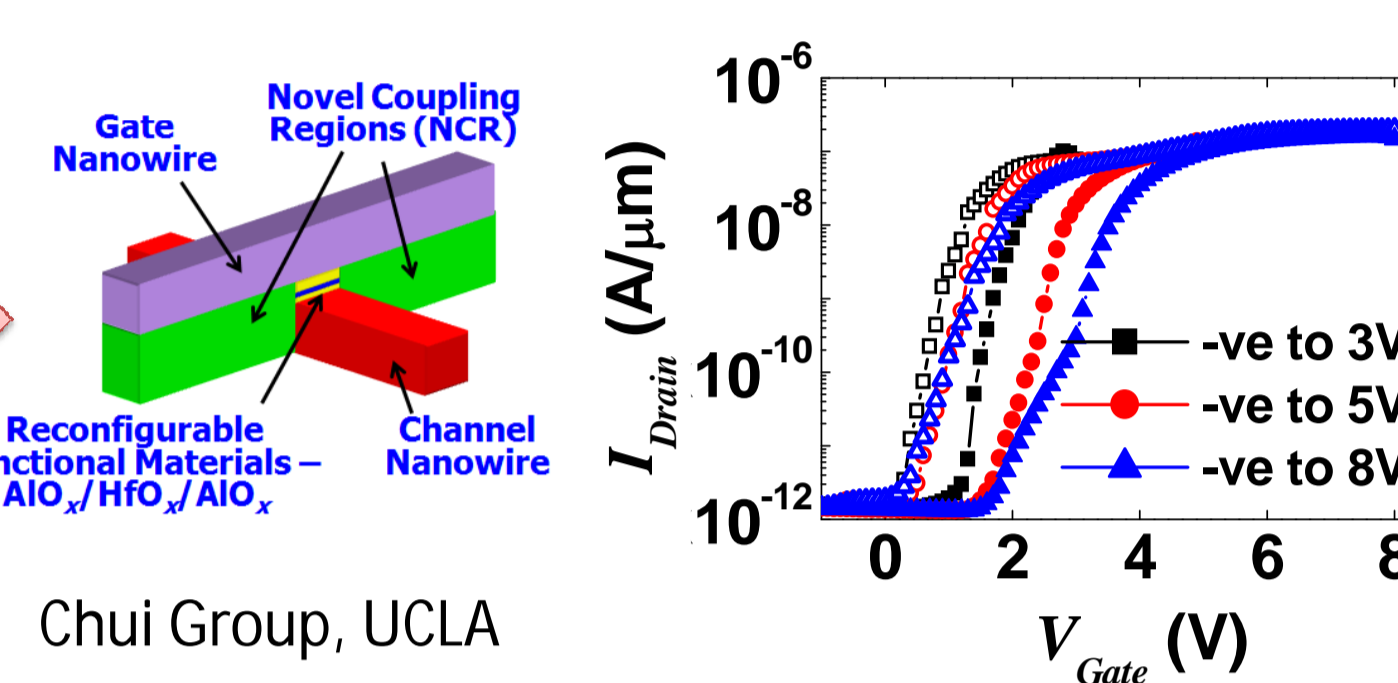
New Material: Silicon Nanowires



FPGA: Emulated Reconfiguration



Reconfigurable Cross-Nanowire FET (xnfWET)

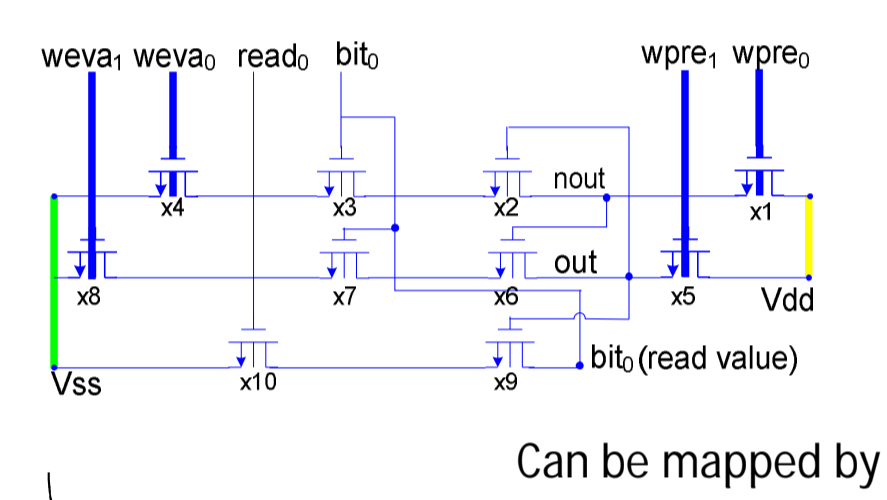


Chui Group, UCLA

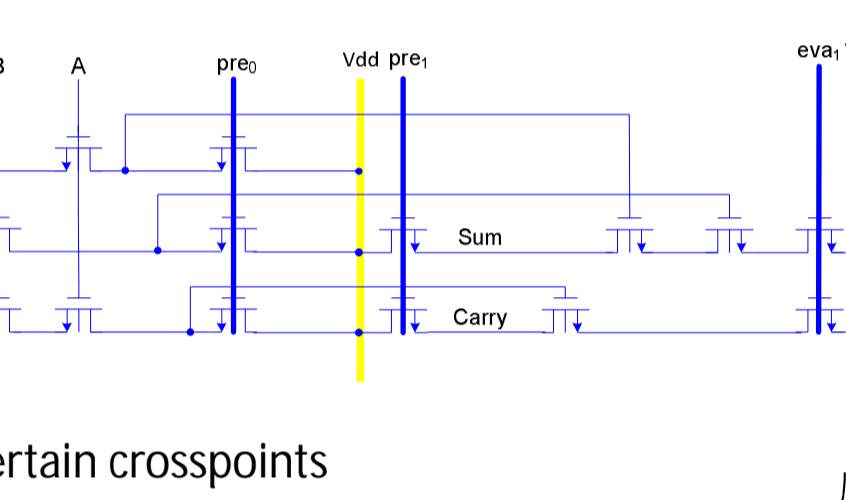
New Concepts

- Fine-grained reconfigurability at device-level
- Novel circuits for volatile memory/logic that can be mapped into uniform grid-based nanowire tiles

Volatile Memory Cell Circuit

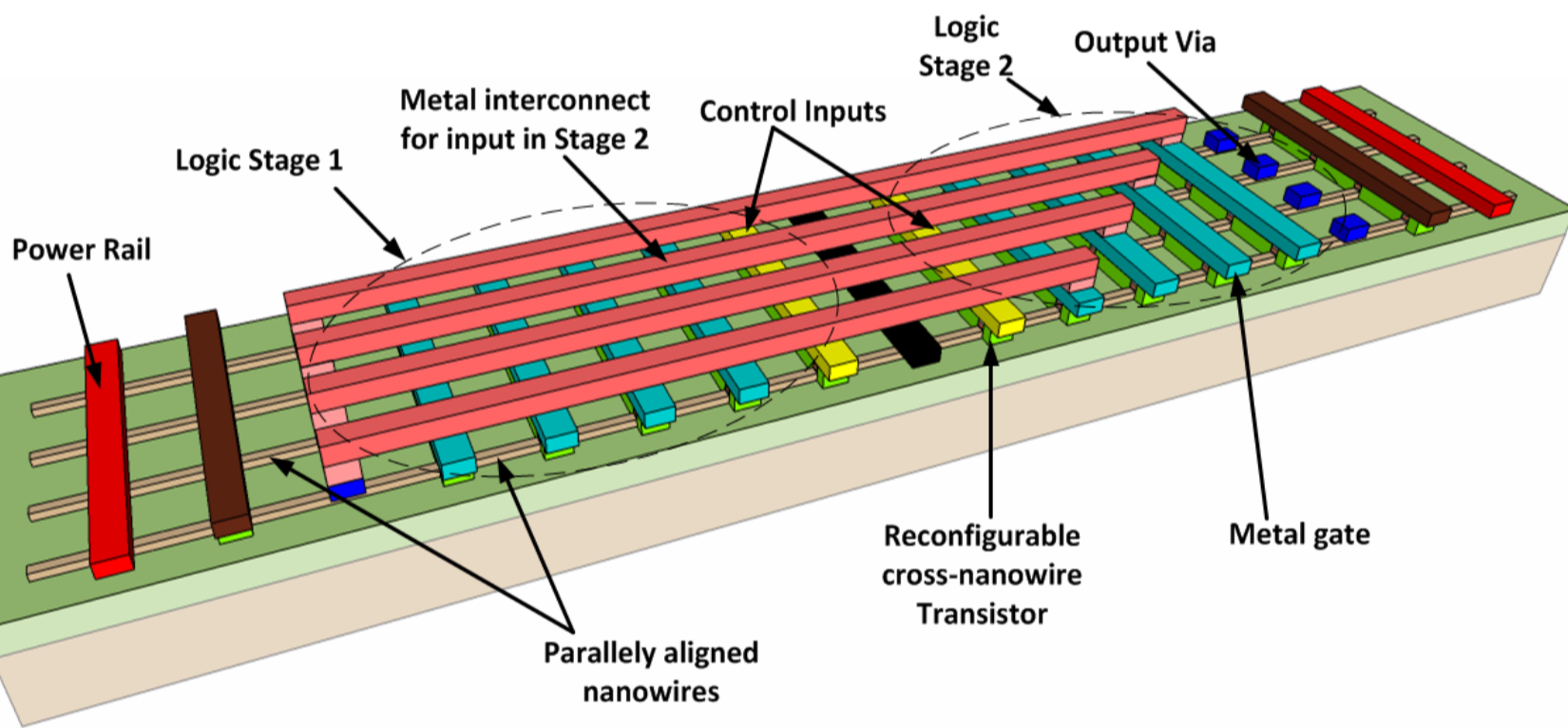


Logic Circuit (Adder)



Can be mapped by programming certain crosspoints

Nanowire-based Reconfigurable Fabric: Nano-FPGA

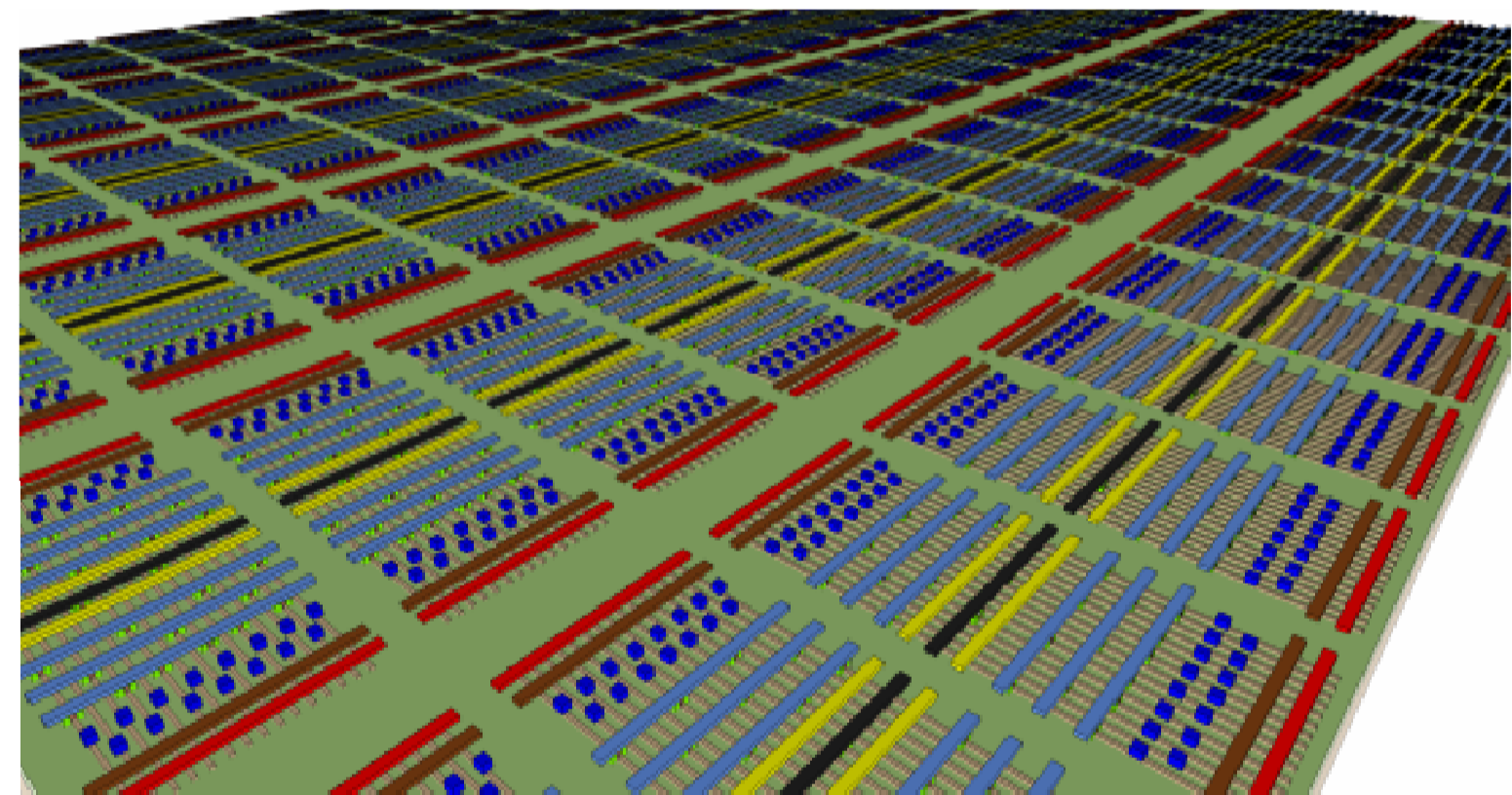


Benchmarking of WISP-0 Nanoprocessor

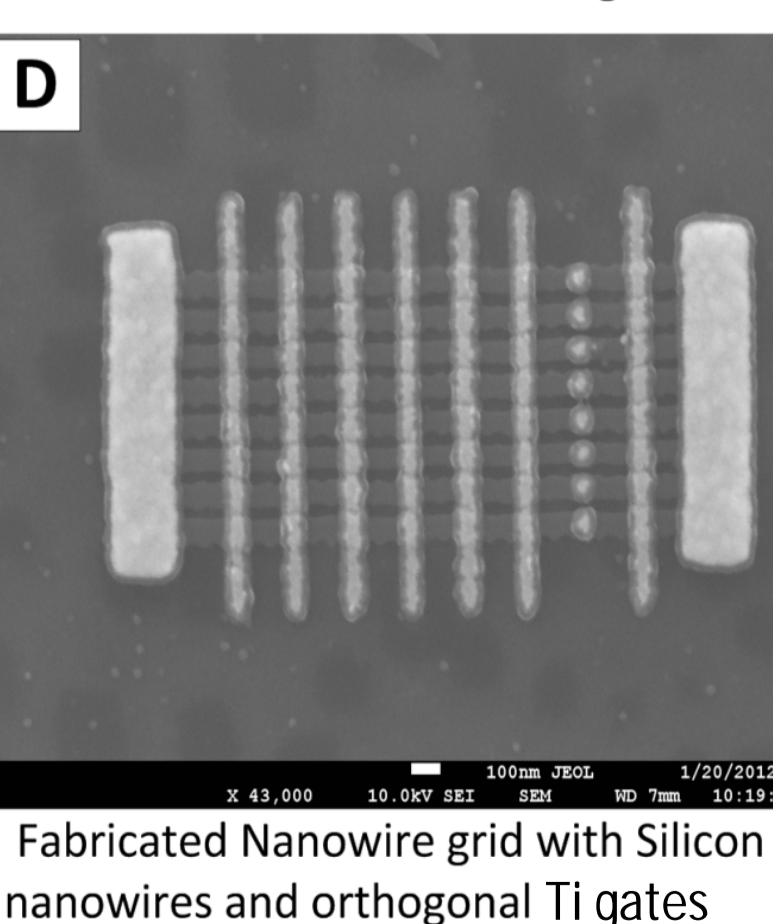
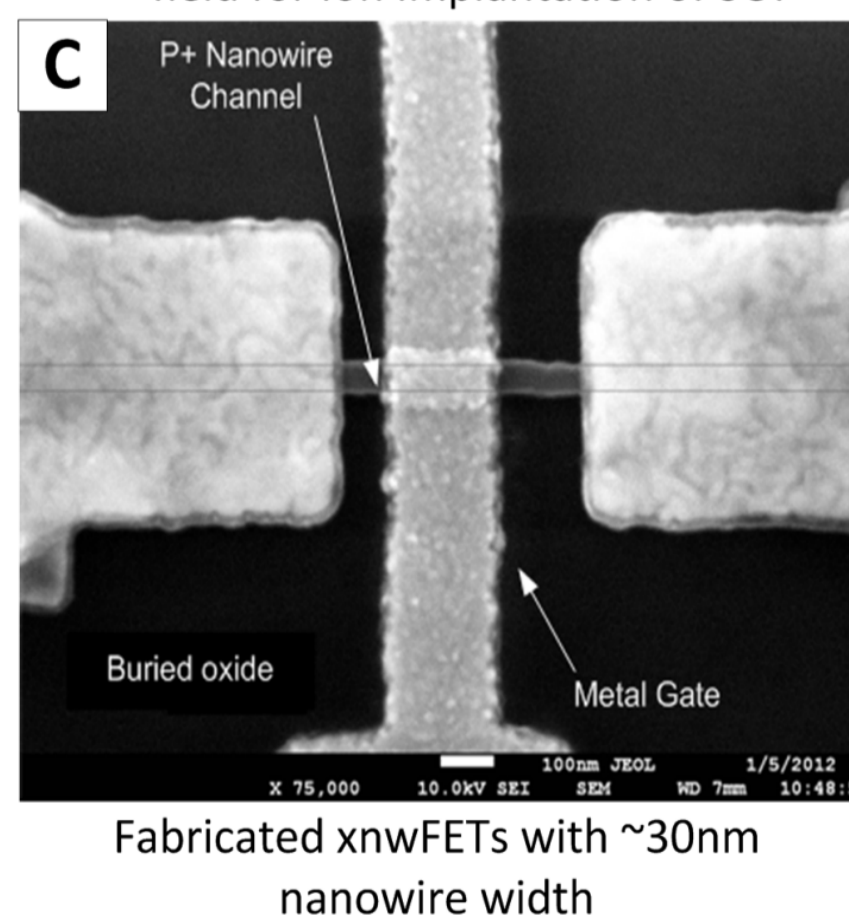
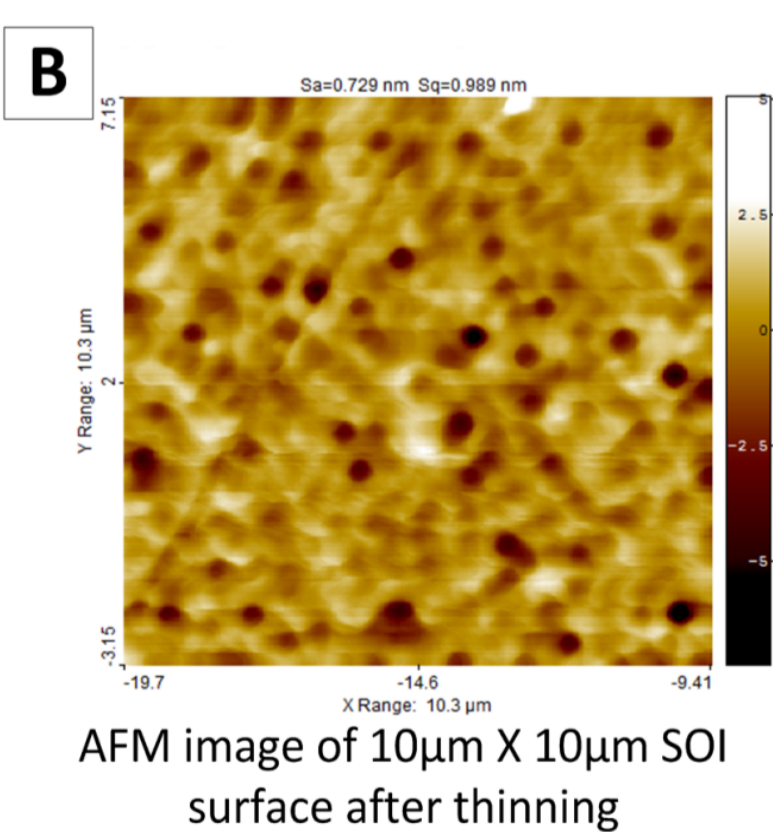
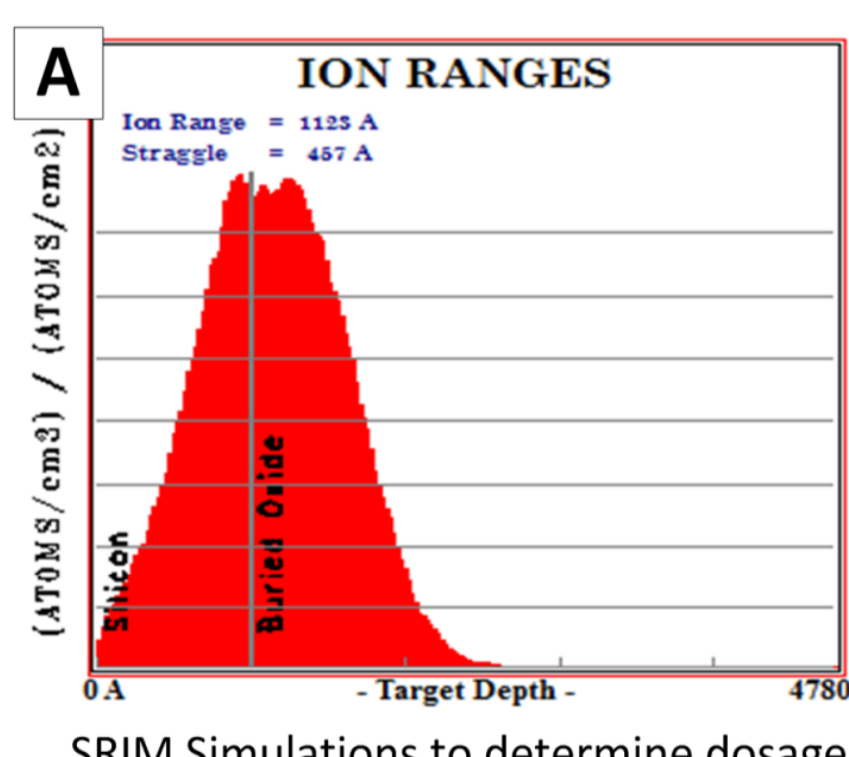
	Area	Power	Performance
Nano-FPGA			
Vs. Projected 16nm CMOS FPGAs	54x	50x	17x

Vision

- Unified nanowire fabric for logic & memory targeting efficient, low-cost reconfigurable systems

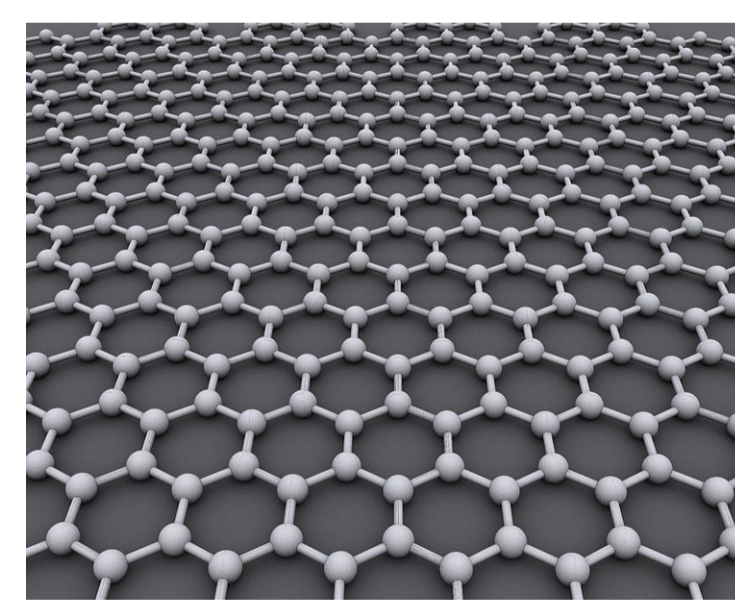


Experimental Effort

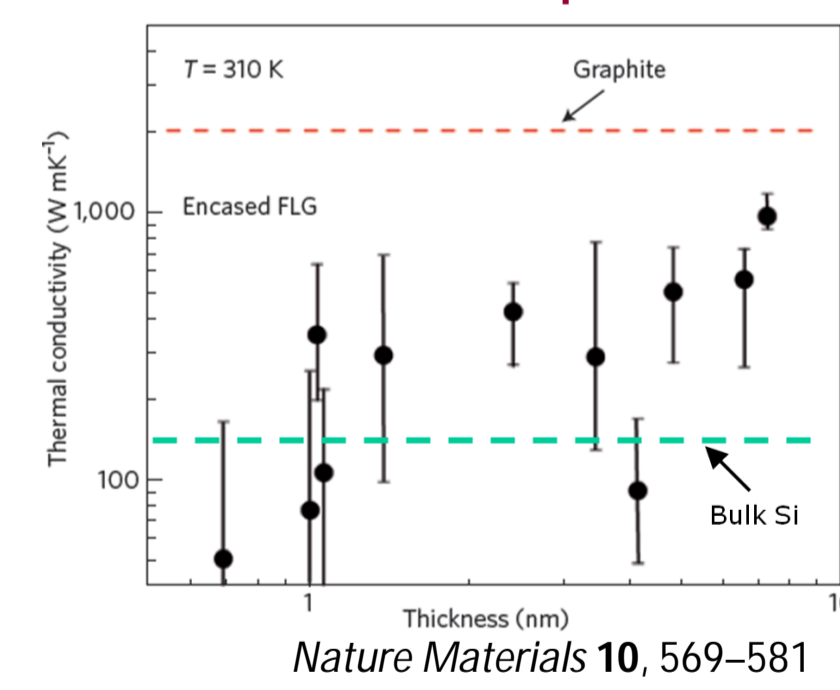


Thermal Management

Graphene



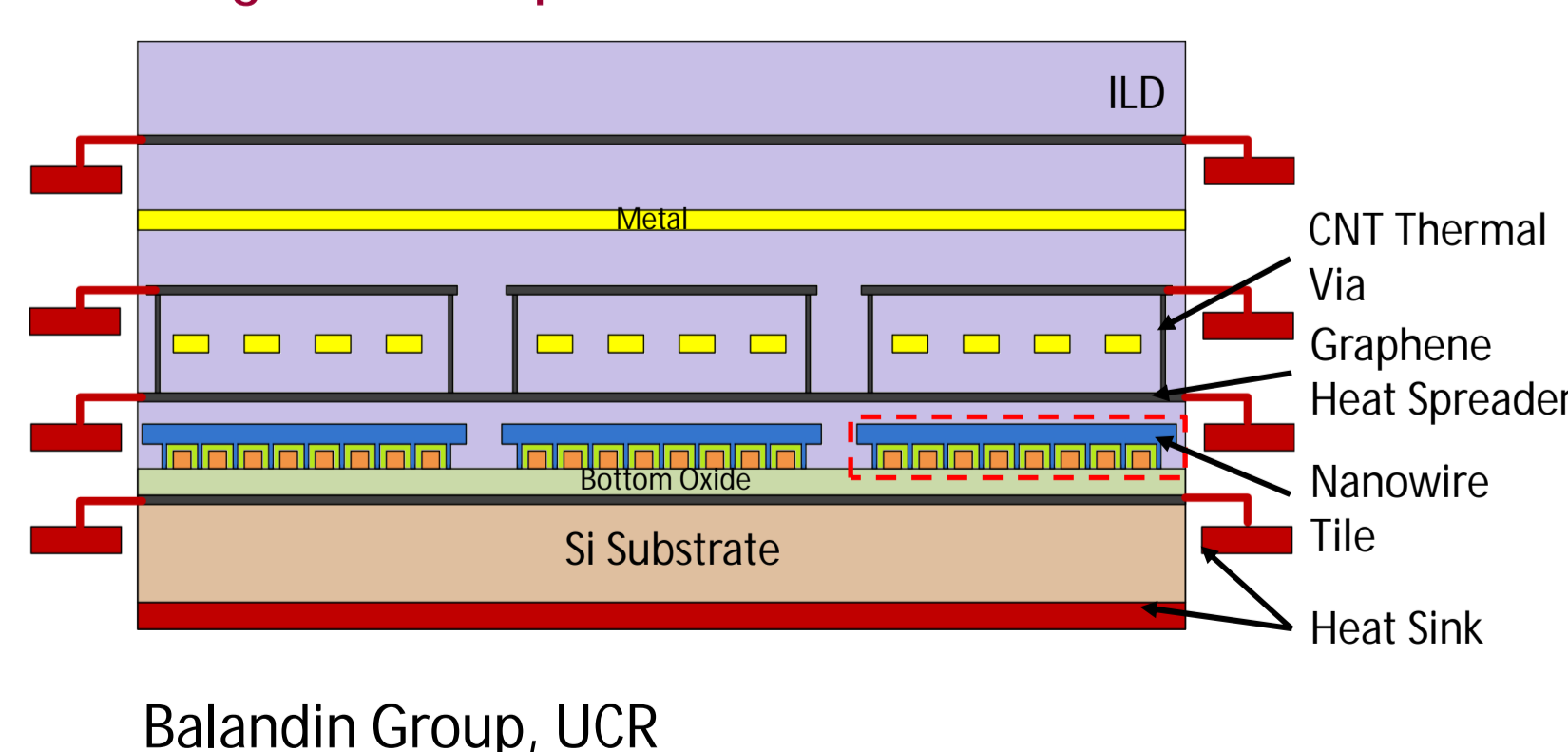
Thermal Conductivity of Encased Graphene



Source: Wikipedia

Nature Materials 10, 569-581

Integrated Graphene Thermal Network

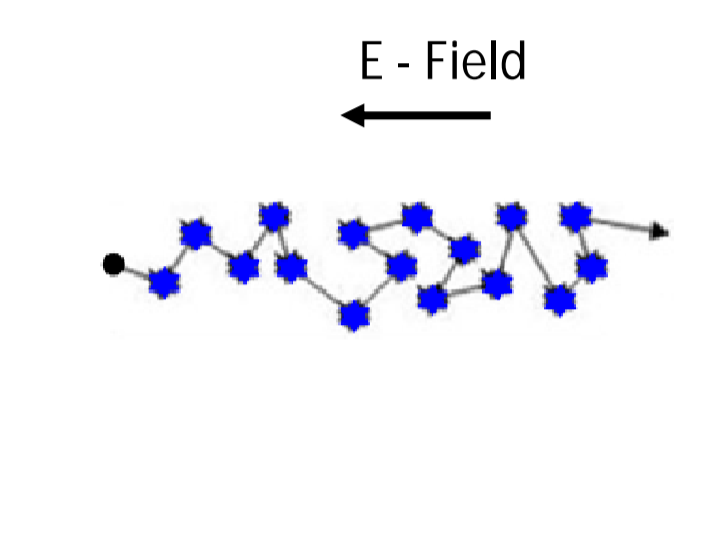


Balandin Group, UCR

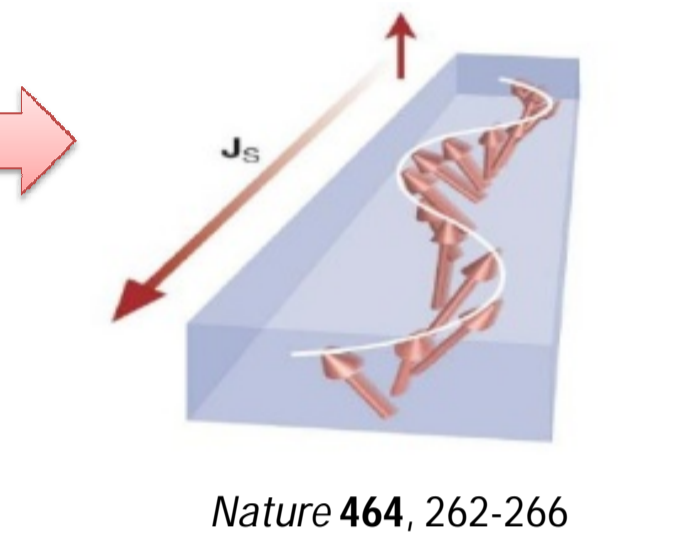
Spin Wave Functions

New Physical Phenomenon: Electron Spin

Current: Electrical Charge based Computation

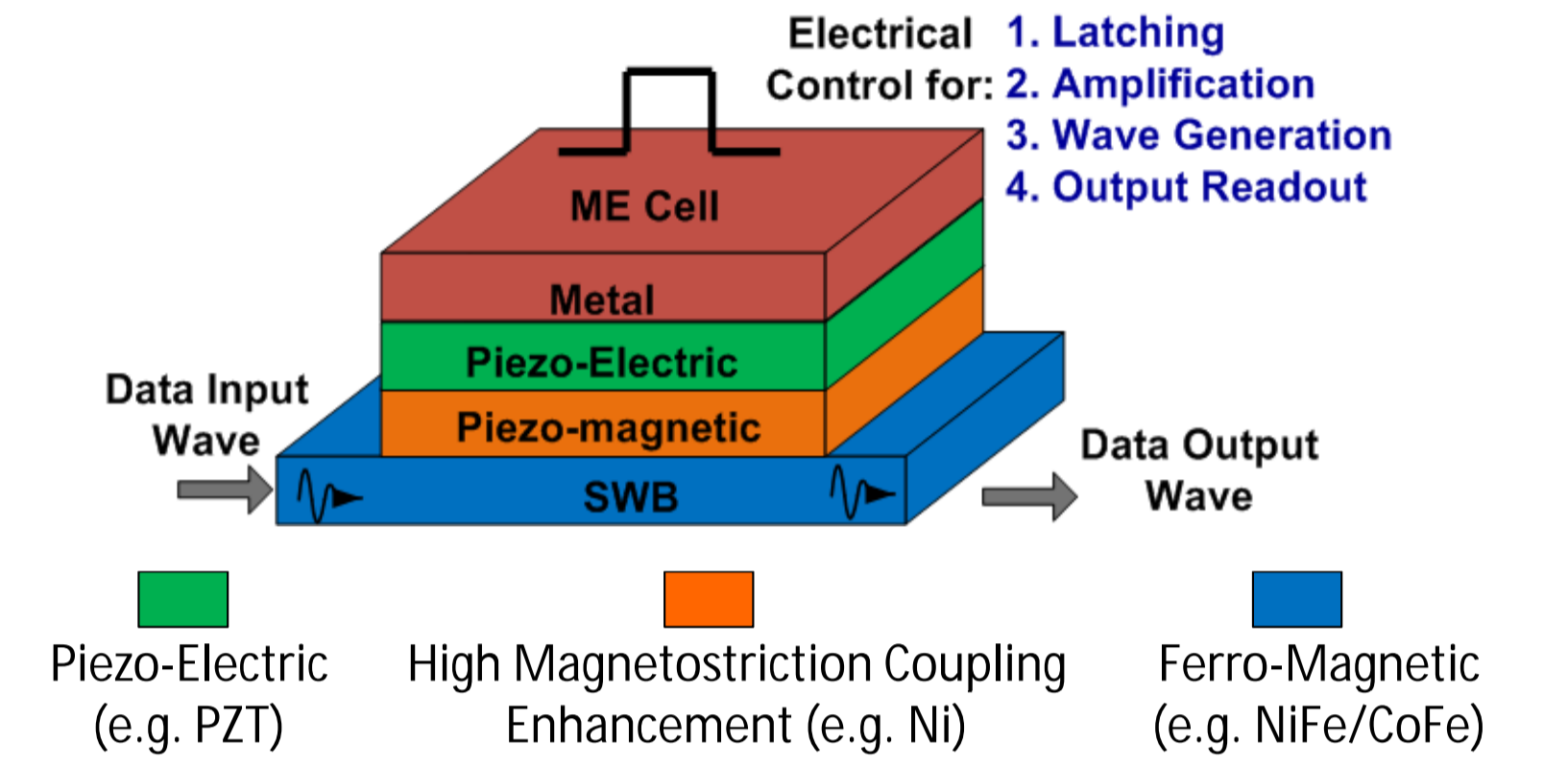


Proposed: Electron Spin based Computation



Nature 464, 262-266

Magneto-Electric Cell

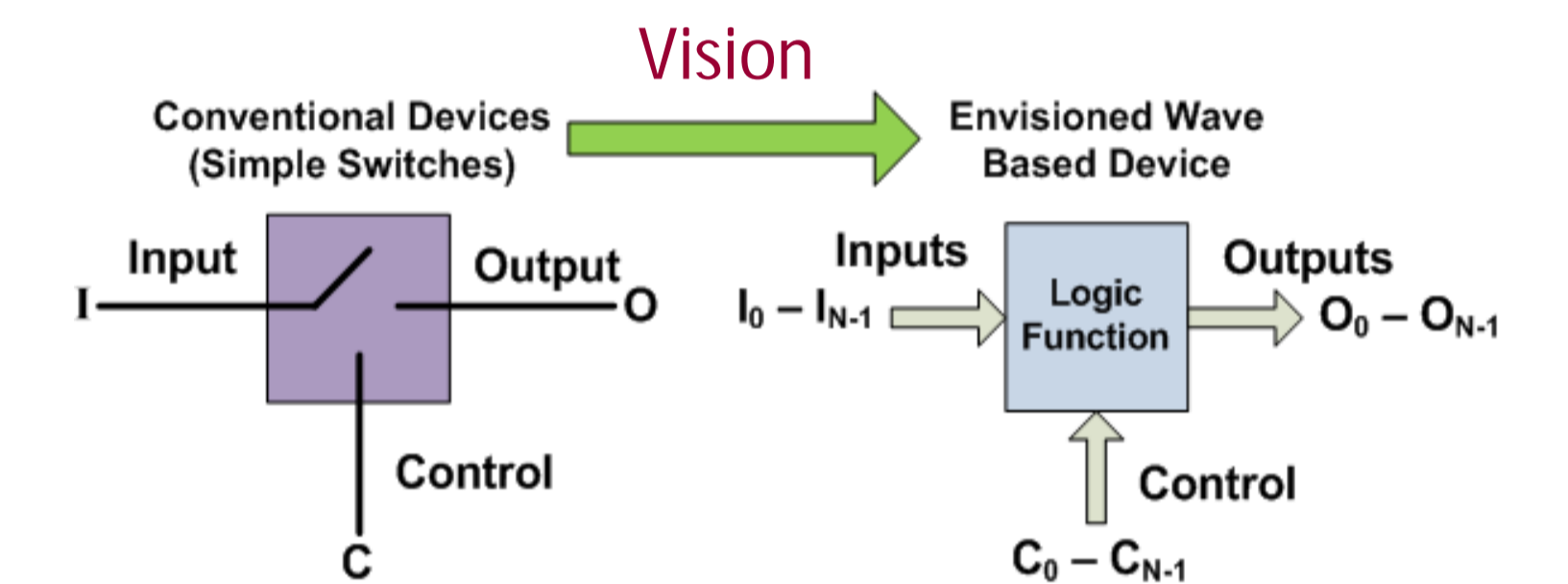


New Concepts

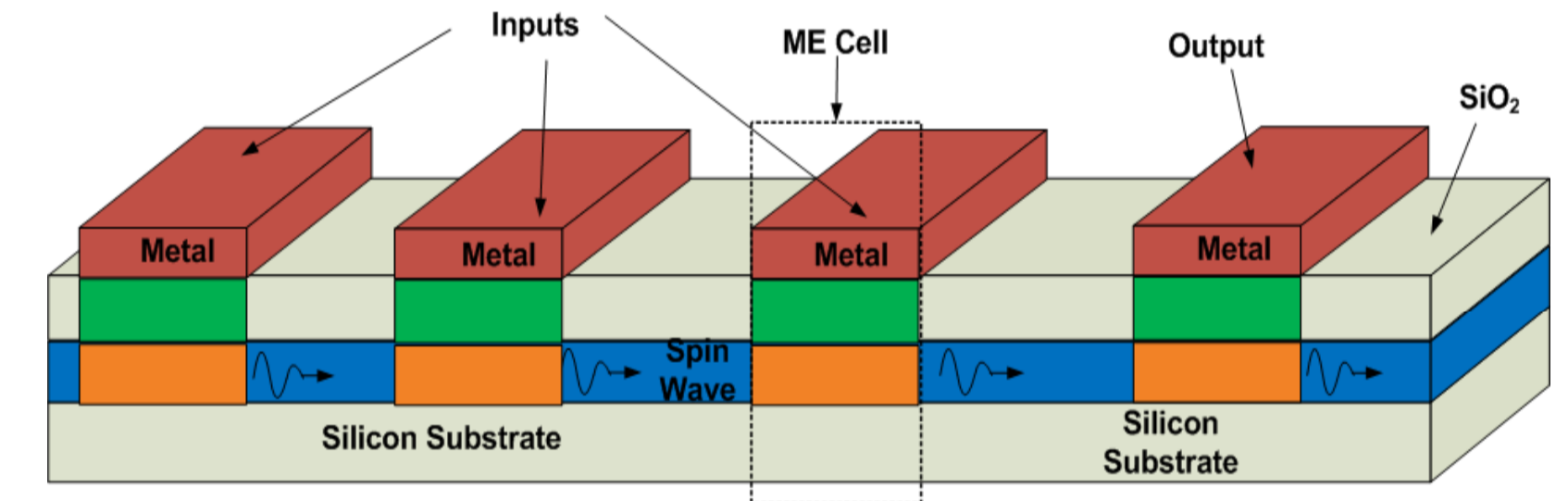
- Non-volatile computing: Logic & Memory
- Leveraging collective precession of spins in ferro-magnetic materials

Vision: Spin Wave Functions (SPWFs)

- Encode information in amplitude and phase of spin-wave; Computation based on wave superposition
- Multi-valued representation; No charge transport → Low power

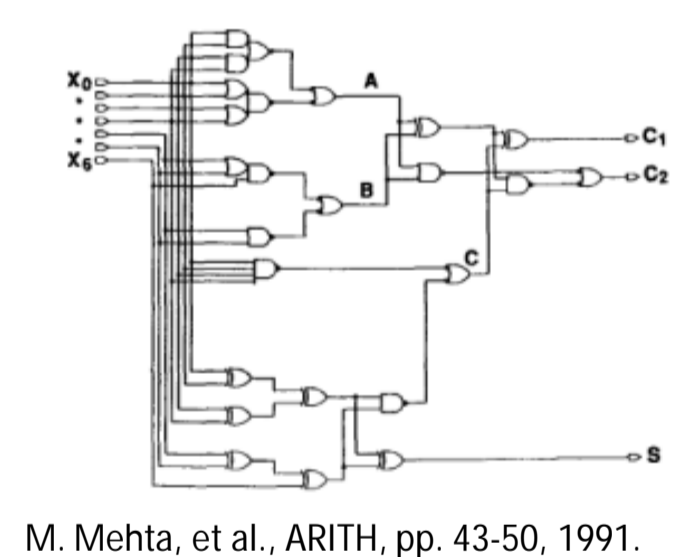


Spin Wave Logic Functions (SPWFs)



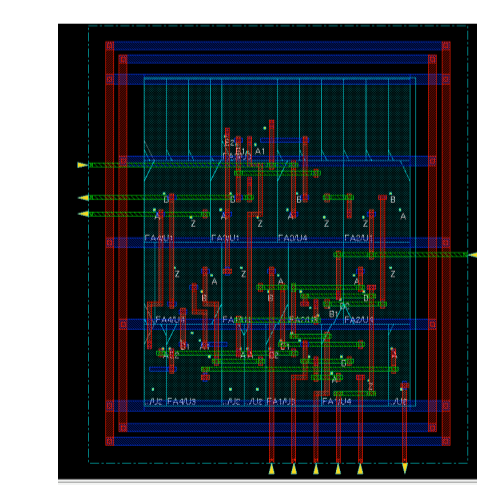
Benchmarking SPWF Logic vs. Other Approaches: 7/3 Counter

Conventional Boolean Logic (Highly Complex)

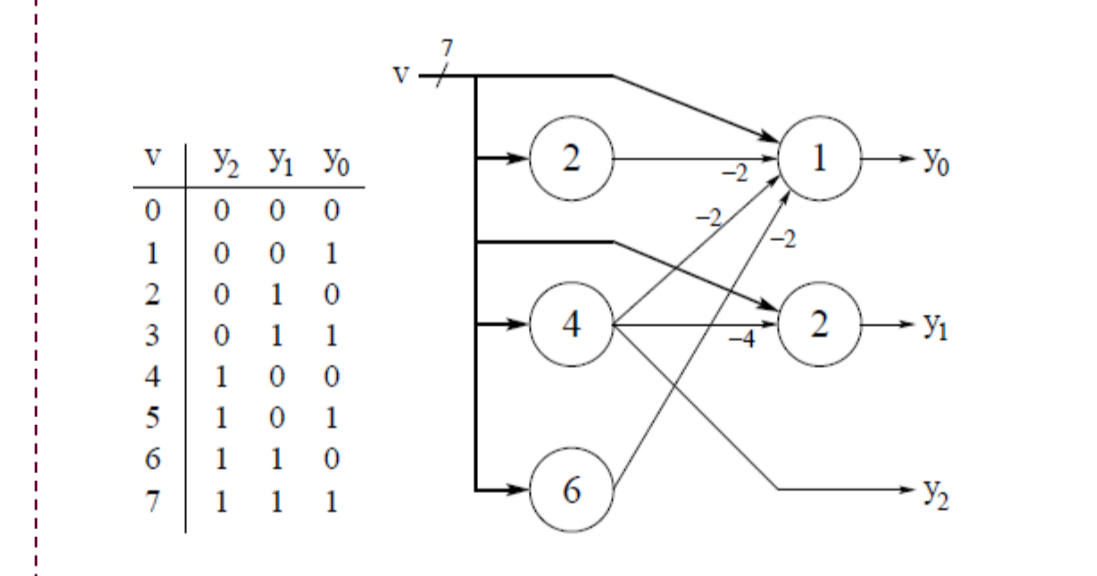


M. Mehta, et al., ARITH, pp. 43-50, 1991.

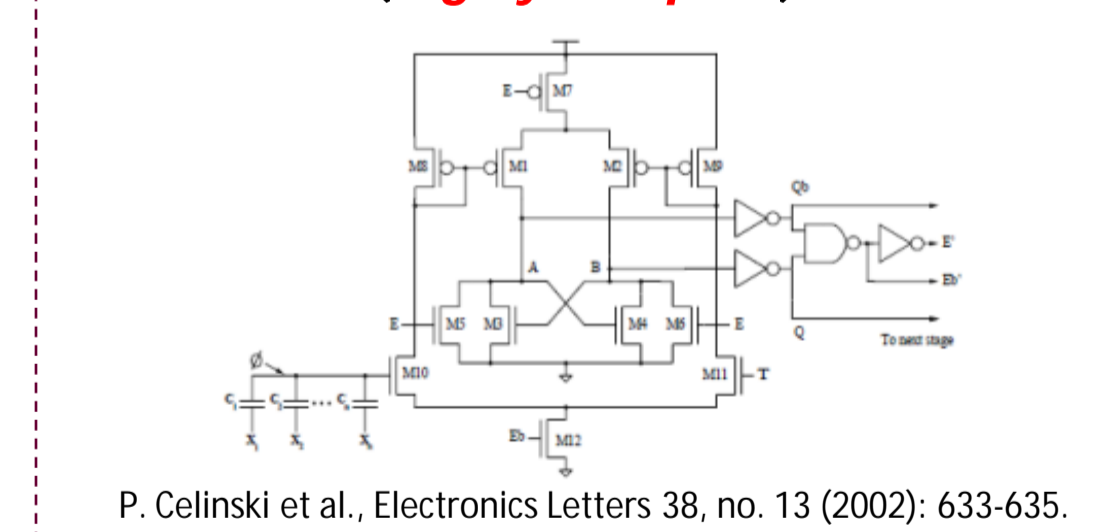
45nm Standard Cell Library based CMOS Layout for (7;3) Counter



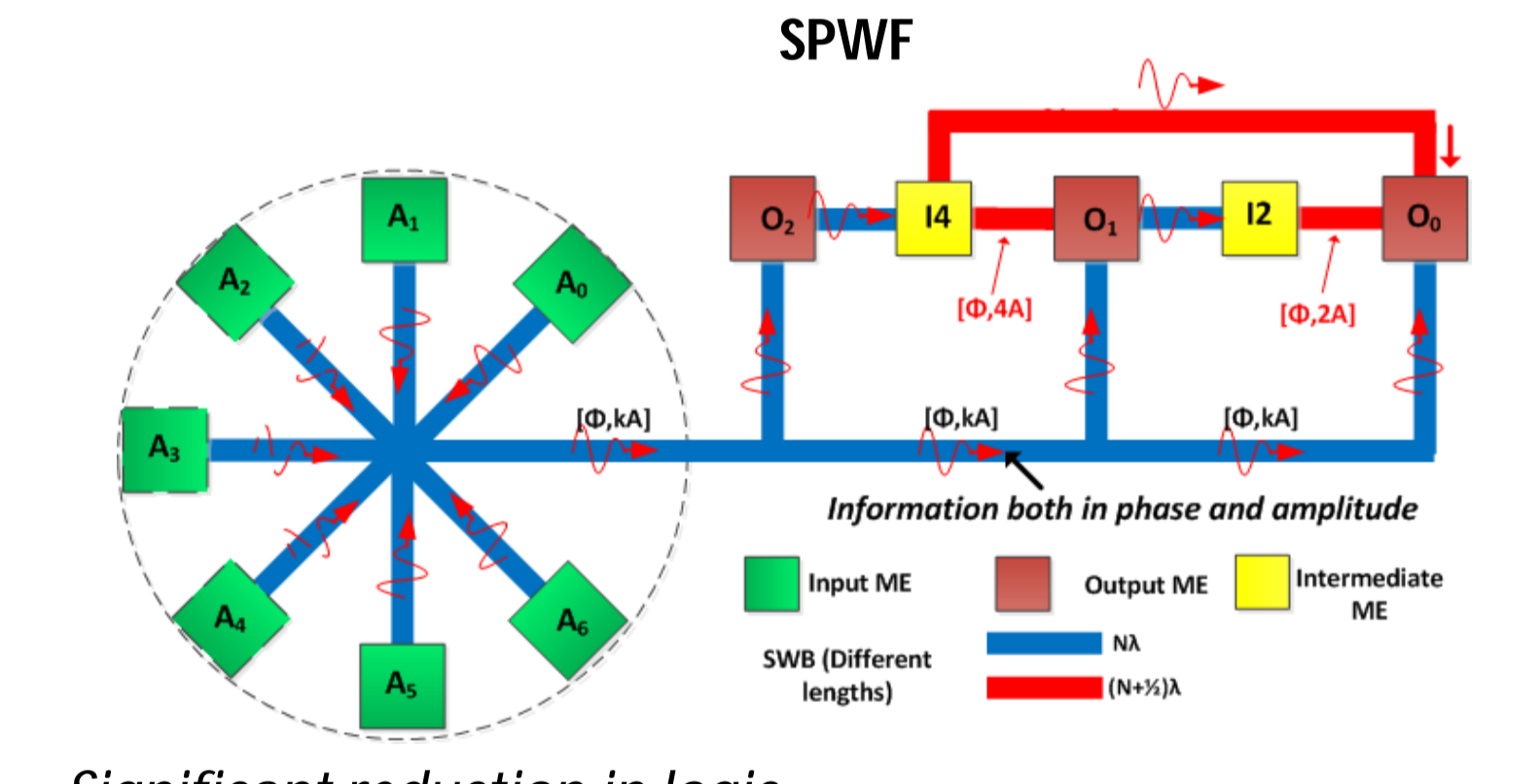
Threshold Logic (Few threshold gates, but individual gates Highly Complex)



MOSFET based Threshold Logic Gate (Highly Complex)



P. Celinski et al., Electronics Letters 38, no. 13 (2002): 633-635.

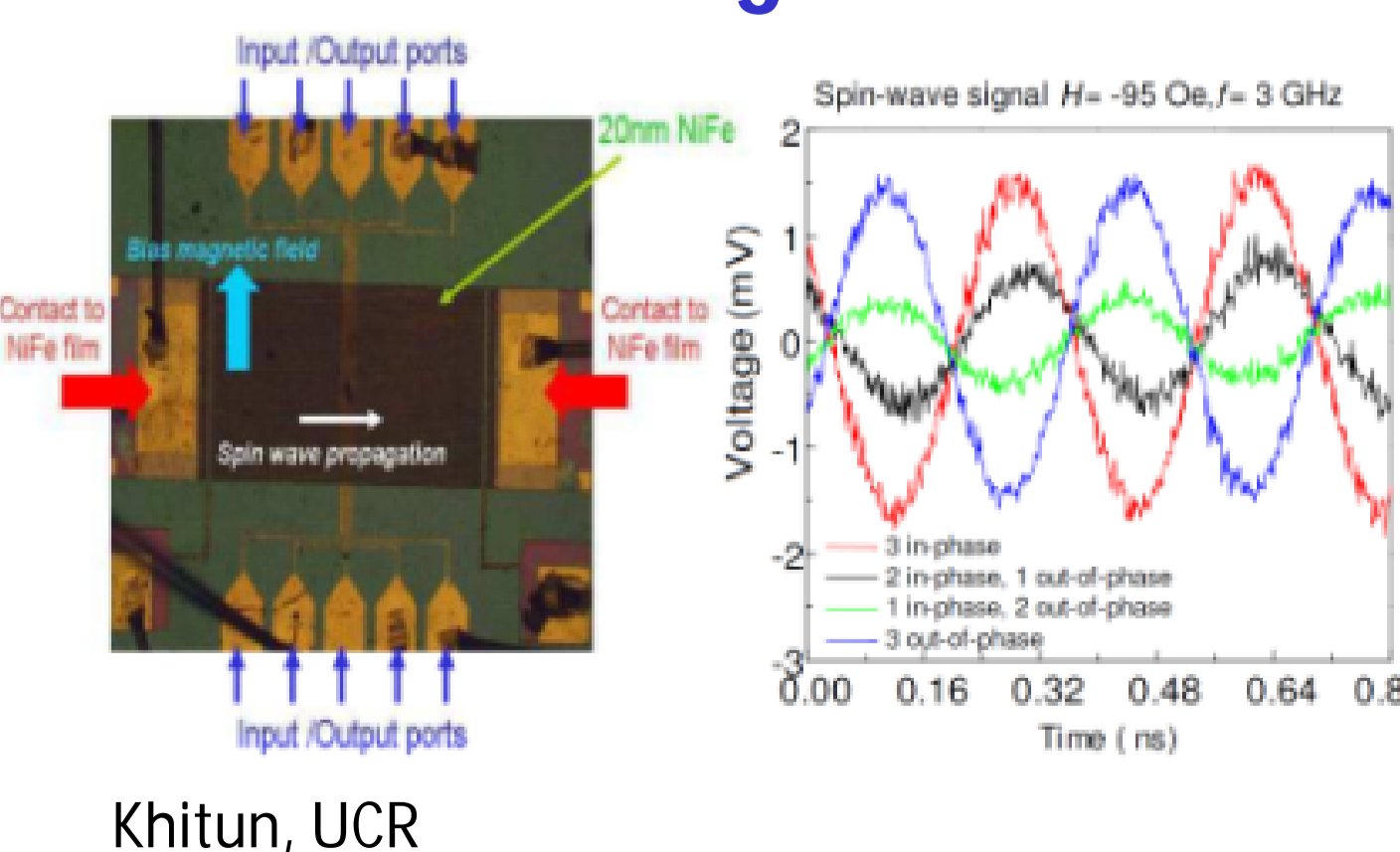


Significant reduction in logic complexity

- ME Cell Assumptions:
 - Switching delay: 100 ps
 - Area: 100nm X 100nm
 - Energy: 10 aJ/operation
- Spin-Wave Bus Assumptions:
 - Velocity: 10⁴ m/s
 - Width/spacing: 100 nm/45 nm
 - Min. Length: at least equal to wavelength of spin waves (λ)
 - λ = 100nm

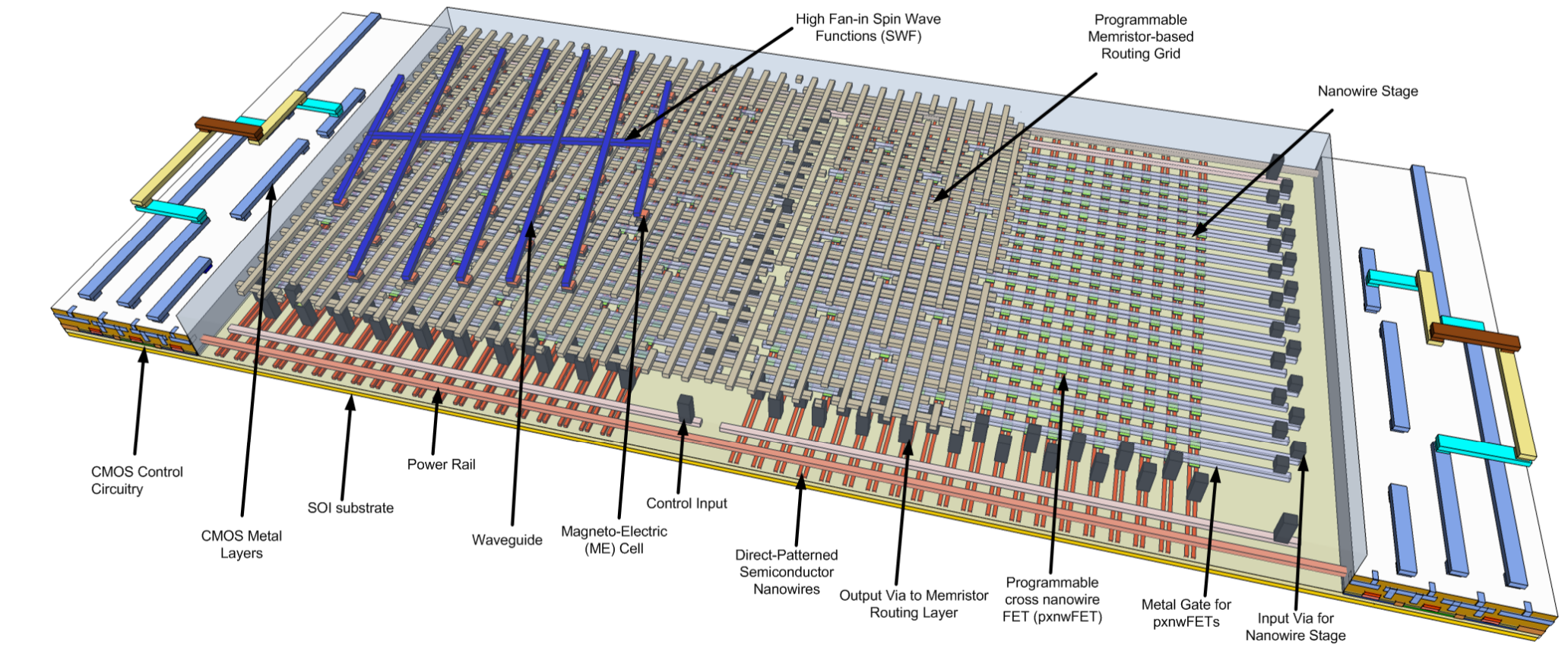
CMOS		
Area (µm ²)	Delay (ps)	Power (µW)
27	740	14
SPWF		
Area (µm ²)	Delay (ps)	Power (µW)
0.2	670	0.2

Experimental: Spin Wave Majority Logic

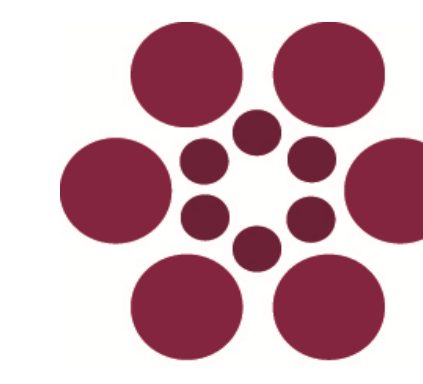


Khitun, UCR

Hybrid Spin-Charge Reconfigurable Fabric



National Science Foundation
WHERE DISCOVERIES BEGIN



Center for Hierarchical Manufacturing